RFMi
BRAND OF AKOUSTIS

RoHS compliant

CDR2000

2595 MHz Ceramic Filter

Package Dimensions

15 x 6.4 x 4.4 mm

ELECTRICAL CHARACTERISTICS:

This filter satisfies Table 1 at Temperature Range : -40 to +85℃

CENTER FREQUENCY :fo=2595 MHz

PASSBAND WIDTH :2515~2675 MHz

INPUT/OUTPUT IMPEDANCE :50Ω

Max. INPUT POWER : 10 W

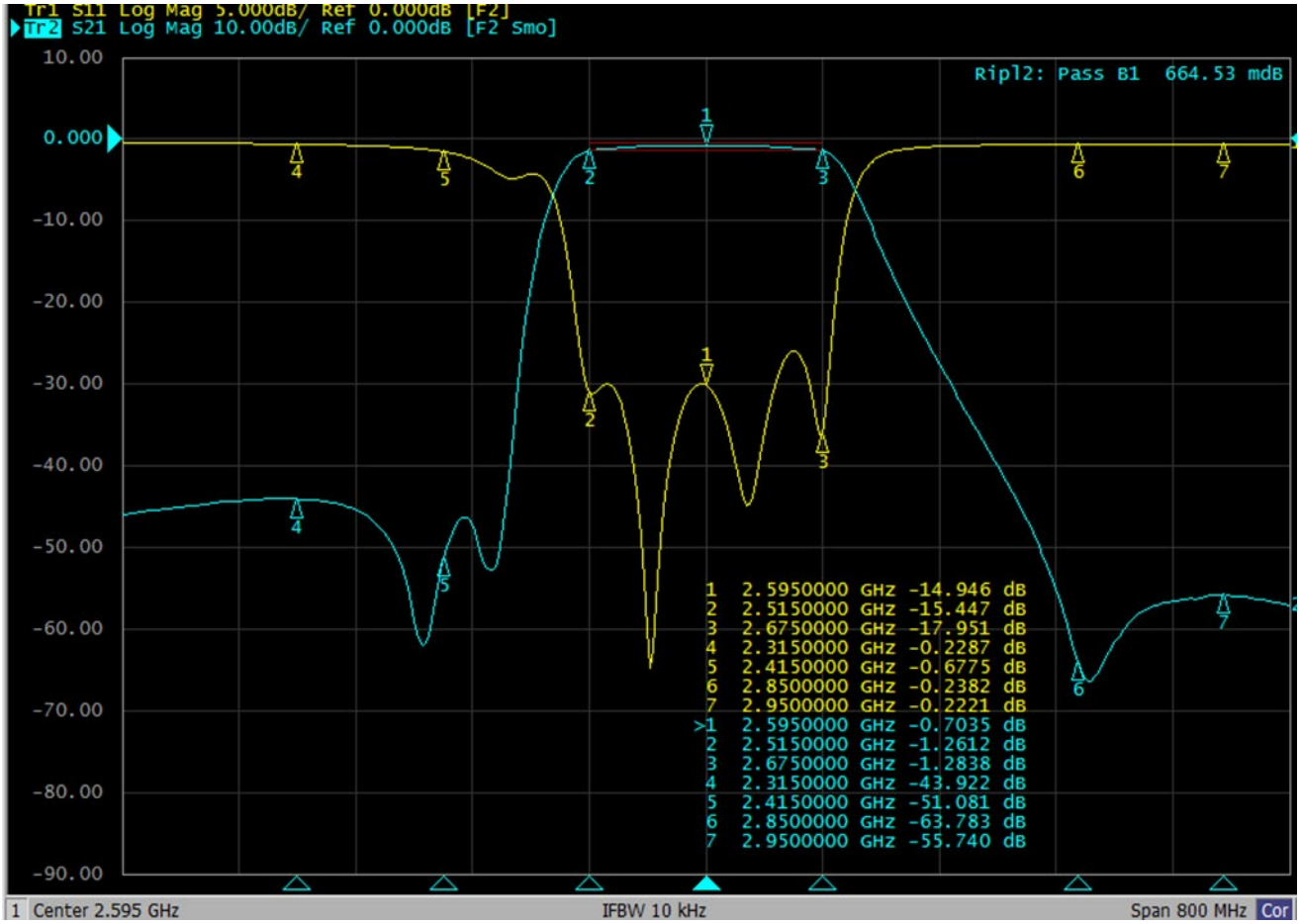
Moisture Sensitivity Level: 2a

TABLE 1

NO.	ITEM		SPECIFICATION	
			Min	Max
1	PASS BAND INSERTION LOSS			1.5 dB
2	PASS BAND RIPPLE			1.0 dB
3	PASS BAND RETURN LOSS		10 dB	
4	STOP—BAND ATTENUATION	at 2315~2415 MHz	30 dB	
		at 2850~2950 MHz	40 dB	
Item NO.4 specifies the absolute value of attenuation.				

※Data is measured on the manufacturer's EVB board

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Tr1 S11 Log Mag 5.000dB/ Ref 0.000dB [F2]
Tr2 S21 Log Mag 10.00dB/ Ref 0.000dB [F2 Smo]
Ripl2: Pass B1 664.53 mdB
10.00
0.000
-10.00
-20.00
-30.00
-40.00
-50.00
-60.00
-70.00
-80.00
-90.00
1 2.5950000 GHz -14.946 dB
2 2.5150000 GHz -15.447 dB
3 2.6750000 GHz -17.951 dB
4 2.3150000 GHz -0.2287 dB
5 2.4150000 GHz -0.6775 dB
6 2.8500000 GHz -0.2382 dB
7 2.9500000 GHz -0.2221 dB
>1 2.5950000 GHz -0.7035 dB
2 2.5150000 GHz -1.2612 dB
3 2.6750000 GHz -1.2838 dB
4 2.3150000 GHz -43.922 dB
5 2.4150000 GHz -51.081 dB
6 2.8500000 GHz -63.783 dB
7 2.9500000 GHz -55.740 dB
1 Center 2.595 GHz
IFBW 10 kHz
Span 800 MHz
Cor

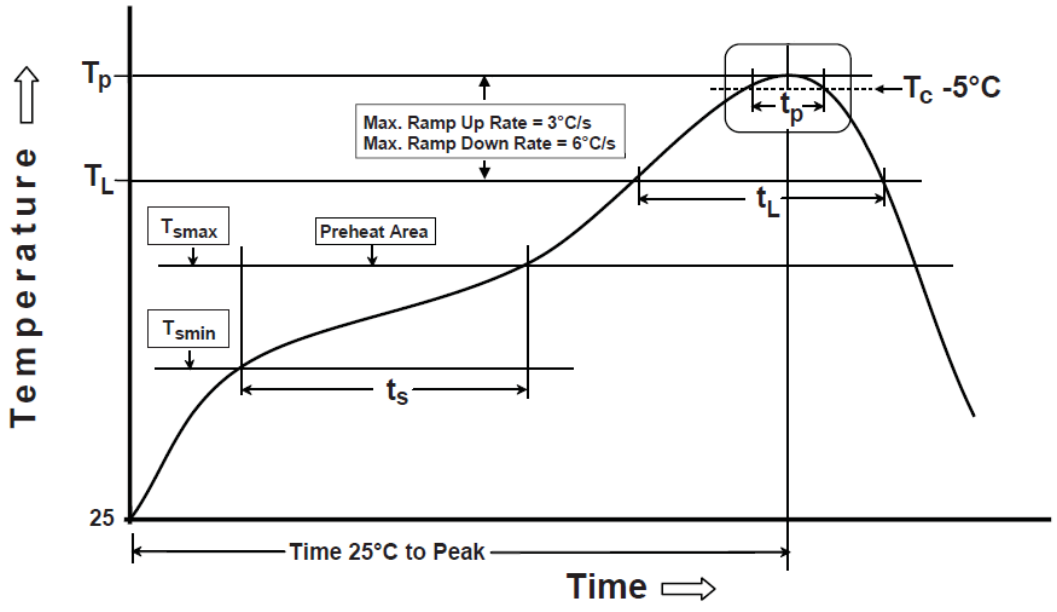
2 Recommended Reflow Soldering Profile

The products can be assembled following Pb-free assembly. According to the Standard **IPC/ JEDEC J-STD-020C**, the temperature profile suggested is as follow:

Phase	Profile features	Pb-Free Assembly (SnAgCu)
PREHEAT	-Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(ts) form (Tsmin to Tsmax)	150℃ 200℃ 60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3℃/second(max)
REFLOW	-Temperature(TL) -Total Time above TL (t L)	217℃ 30-100 seconds
PEAK	-Temperature(TP) -Time(tp)	260℃ 3 second
RAMP-DOWN	Rate	6℃ / second max.
Time from 25℃ to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
Solder Paste Model		SHENMAO PF606-P26

Note：All the temperature measure point is on top surface of the component, if temperature over recommend, it will make component surface peeling or damage.

The graphic shows temperature profile for component assembly process in reflow ovens



Soldering With Iron:

Soldering condition : Soldering iron temperature 270±10 ℃.

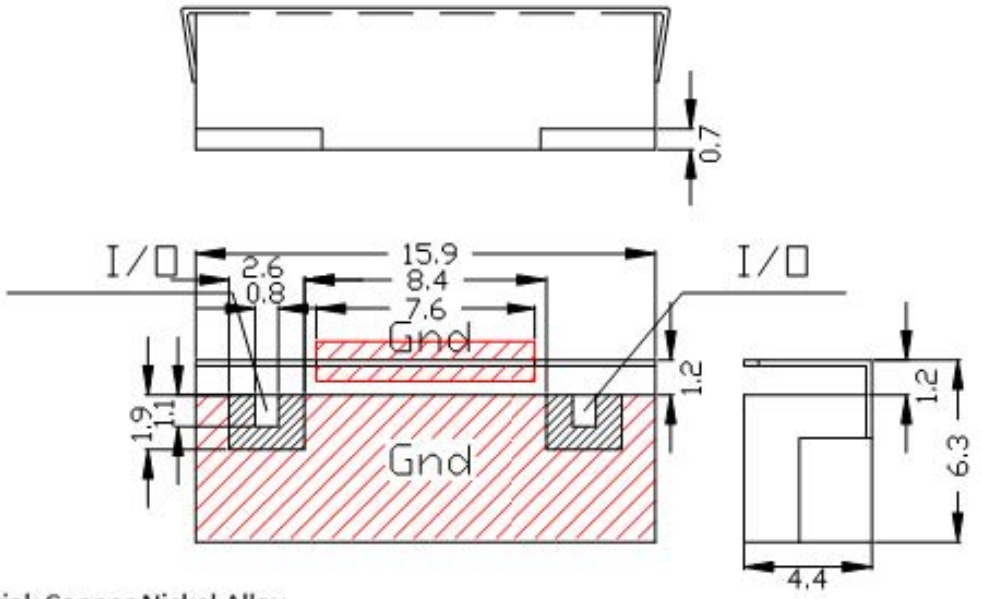
Apply preheating at 120℃ for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron over temperature 270±10 ℃ or 3 seconds, it will make component surface peeling or damage.

Soldering iron can not leakage of electricity.

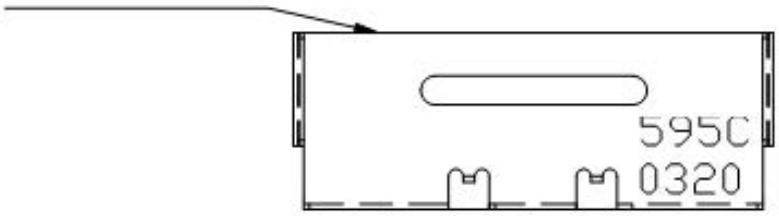
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3.DIMENSION AND PCB LAYOUT

3-1 SHAPE AND DIMENSION



Case Material: Copper Nickel Alloy



I/O: Input / Output
Gnd:Ground

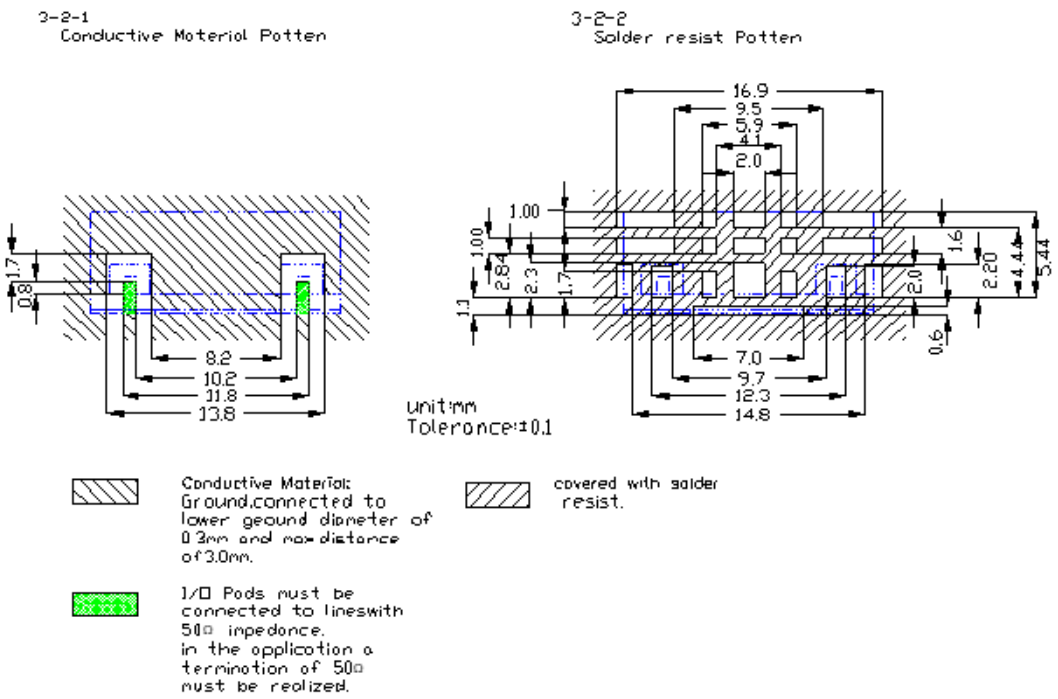
595C: product name(J2595C)
0320: month/year(03/2020)
Color: Black

Unit:mm
Tolerance:±0.3

3-2 PCB RECOMMENDED PATTERN FOR FILTER

Note: Test PCB material: FR4 4.6, 1.0mm.

The filter use limit: the layout goes away PCB edge.



CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.